

# UK Patent Application

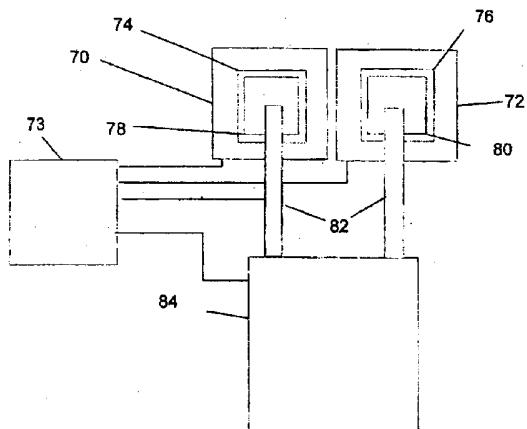
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(54) Abstract Title: **Method and apparatus for laser processing**

(57) A method and an apparatus for processing workpieces with a laser beam (89) include first and second stages (74,76) for holding the workpieces (78,80) and first and second laser beam paths. The first workpiece is loaded upon the first stage, aligned with the first laser beam path, and processing begun. While the first workpiece is aligned in relation to the first laser beam path, the second workpiece is prepared in relation to the second laser beam path. Processing of the second workpiece is begun as soon as the laser beam is available for processing.



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